# NSS1C200MZ4, NSV1C200MZ4 100 V, 2.0 A, Low V<sub>CE(sat)</sub> **PNP Transistor**

ON Semiconductor's e<sup>2</sup>PowerEdge family of low V<sub>CE(sat)</sub> transistors are miniature surface mount devices featuring ultra low saturation voltage (V<sub>CE(sat)</sub>) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-140	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-7.0	Vdc
Base Current – Continuous	Ι <sub>Β</sub>	1.0	Α
Collector Current – Continuous	Ι <sub>C</sub>	2.0	А
Collector Current – Peak	I <sub>CM</sub>	3.0	А

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 1)	155	°C/W
Total Device Dissipation T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 2)	2.0 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 2)	64	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

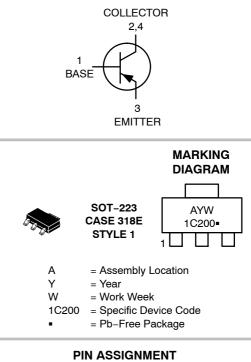
1. FR-4 @ 7.6 mm<sup>2</sup>, 1 oz. copper traces. 2. FR-4 @ 645 mm<sup>2</sup>, 1 oz. copper traces.

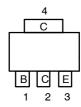


### **ON Semiconductor®**

http://onsemi.com

# -100 VOLTS, 2.0 AMPS PNP LOW V<sub>CE(sat)</sub> TRANSISTOR





Top View Pinout

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS1C200MZ4T1G NSV1C200MZ4T1G	SOT-223 (Pb-Free)	1000/ Tape & Reel
NSS1C200MZ4T3G	SOT-223 (Pb-Free)	4000/ Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

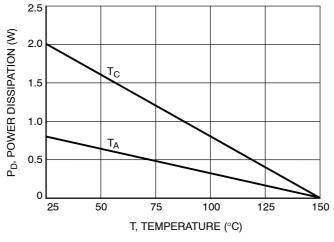
# NSS1C200MZ4, NSV1C200MZ4

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage ( $I_C = -10 \text{ mAdc}, I_B = 0$ )	V <sub>(BR)CEO</sub>	-100			Vdc
Collector – Base Breakdown Voltage ( $I_C = -0.1 \text{ mAdc}, I_E = 0$ )	V <sub>(BR)CBO</sub>	-140			Vdc
Emitter – Base Breakdown Voltage ( $I_E = -0.1 \text{ mAdc}, I_C = 0$ )	V <sub>(BR)EBO</sub>	-7.0			Vdc
Collector Cutoff Current (V <sub>CB</sub> = $-140$ Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>			-100	nAdc
Emitter Cutoff Current (V <sub>EB</sub> = -6.0 Vdc)	I <sub>EBO</sub>			-50	nAdc
ON CHARACTERISTICS					
DC Current Gain (Note 3)	h <sub>FE</sub>				

DC Current Gain (Note 3) $(I_C = -10 \text{ mA}, V_{CE} = -2.0 \text{ V})$ $(I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V})$ $(I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V})$ $(I_C = -2.0 \text{ A}, V_{CE} = -2.0 \text{ V})$	hFE	150 120 80 50		360	
Collector – Emitter Saturation Voltage (Note 3) ( $I_C = -0.1 \text{ A}, I_B = -0.010 \text{ A}$ ) ( $I_C = -0.5 \text{ A}, I_B = -0.050 \text{ A}$ ) ( $I_C = -1.0 \text{ A}, I_B = -0.100 \text{ A}$ ) ( $I_C = -2.0 \text{ A}, I_B = -0.200 \text{ A}$ )	V <sub>CE(sat)</sub>			-0.040 -0.080 -0.125 -0.220	V
Base – Emitter Saturation Voltage (Note 3) $(I_C = -1.0 \text{ A}, I_B = -0.100 \text{ A})$	V <sub>BE(sat)</sub>			-0.950	V
Base – Emitter Turn–on Voltage (Note 3) $(I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V})$	V <sub>BE(on)</sub>			-0.850	V
Cutoff Frequency (I <sub>C</sub> = $-100$ mA, V <sub>CE</sub> = $-5.0$ V, f = $100$ MHz)	f <sub>T</sub>		120		MHz
Input Capacitance (V <sub>EB</sub> = 3.0 V, f = 1.0 MHz)	Cibo		200		pF
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	Cobo		22		pF

3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle  $\leq$  2%.

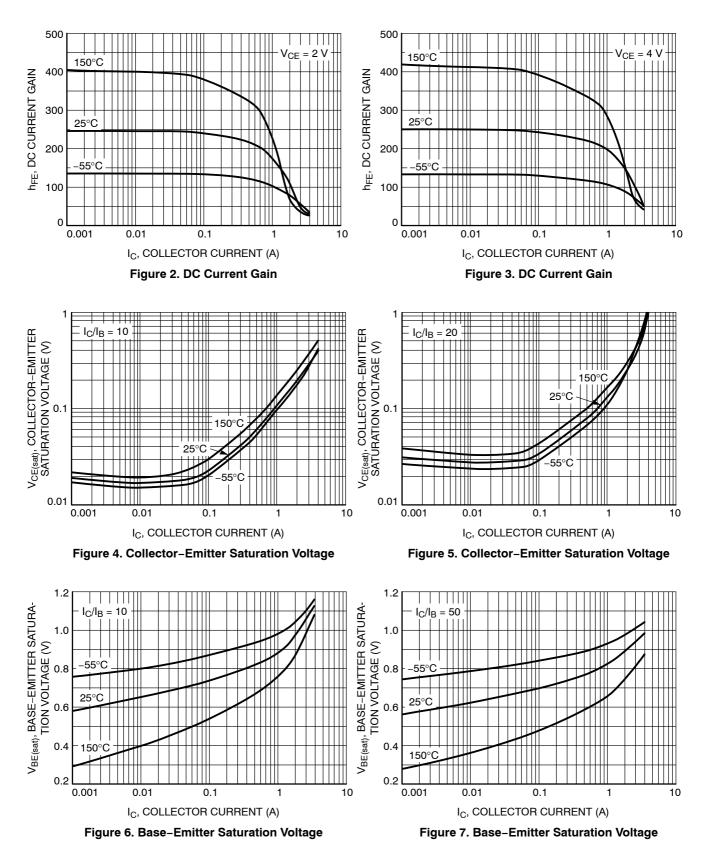


## **TYPICAL CHARACTERISTICS**

Figure 1. Power Derating

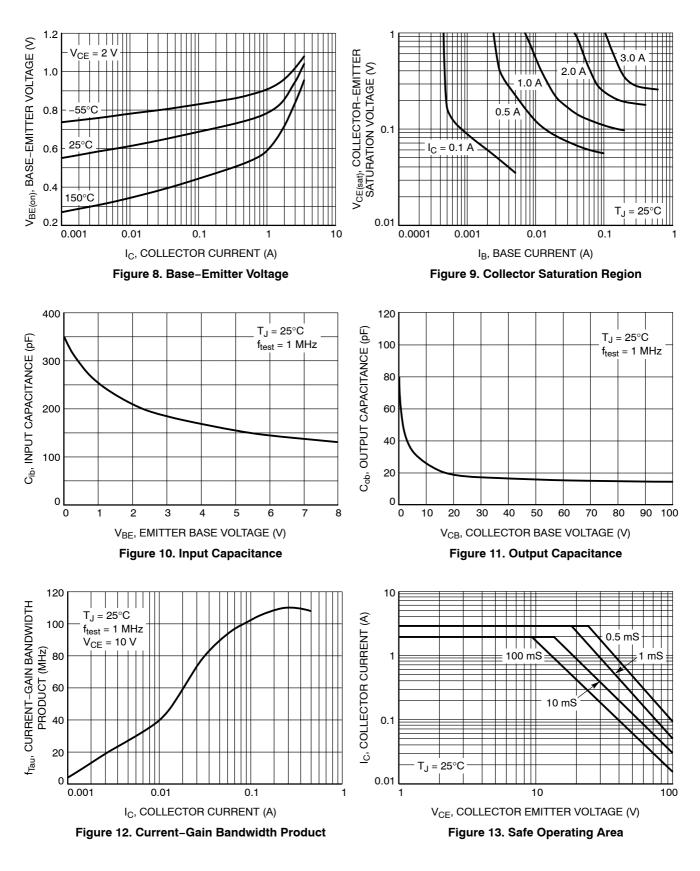
# NSS1C200MZ4, NSV1C200MZ4

### **TYPICAL CHARACTERISTICS**



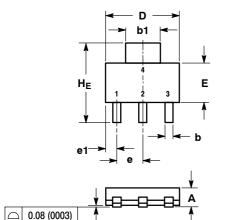
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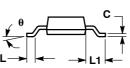
### **TYPICAL CHARACTERISTICS**



#### PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 **ISSUE N** 





<ol> <li>2. CONTROLLING DIMENSION: INCH.</li> </ol>							
	MILLIMETERS		INCHES				
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.50	1.63	1.75	0.060	0.064	0.068	
A1	0.02	0.06	0.10	0.001	0.002	0.004	
b	0.60	0.75	0.89	0.024	0.030	0.035	
b1	2.90	3.06	3.20	0.115	0.121	0.126	
с	0.24	0.29	0.35	0.009	0.012	0.014	
D	6.30	6.50	6.70	0.249	0.256	0.263	
Е	3.30	3.50	3.70	0.130	0.138	0.145	
е	2.20	2.30	2.40	0.087	0.091	0.094	
e1	0.85	0.94	1.05	0.033	0.037	0.041	
L	0.20			0.008			

2.00

7.30

10

0.069

0.276

0.060

0.264

0

0.078

0.287

10

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MICH.

STYLE 1 PIN 1. BASE 2. COLLECTOR 3. EMITTER 4 COLLECTOR

1.50

6.70

0

1.75

7.00

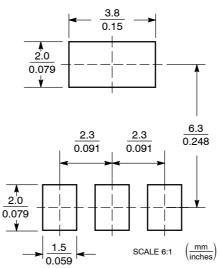
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#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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